

MCNI90100-P52

X-Band Internally Matched GaN Device

Key Features

- Operating Frequency: 9.00-10.00 GHz
- Saturated Output Power (Psat): ≥ 52 dBm
- Power Gain(Gp): ≥ 8 dB
- Work Efficiency (η): ≥ 35%
- Port Matching: Zin/Zout = 50 Ω



Product Description

The MCNI90100-P52 is an internal matching GaN device, which adopts advanced co-planar internal matching MCM and thin film circuit technology. The typical working frequency range is 9.00-10.00GHz. This device can be used in different RF/Microwave system and subsystem. The high output power level, high efficiency and wide operating temperature range can make application very flexible.

Absolute Maximum Ratings (Tc=25°C)

Parameter	Symbol	Value	Unit
Drain-Source Voltage	Vds	40	V
Gate-Source Voltage	Vgs	-5	V
Storage Temperature	Tstg	-65 ~ +150	C
Channel Temperature	Tch	150	°C

*Not recommended to work under these conditions.

Microwave Electrical Characteristics

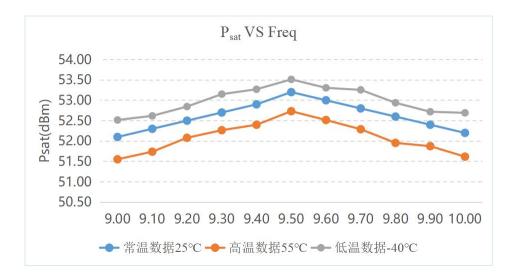
Parameter	Symbol	Test Condition	Min	Тур	Max	Unit
Drain Current	ldsr	VDS:28V Pulse T=1ms,Duty=10% Pin: 44dBm Freq: 9~10GHZ	-	16.2	-	А
Saturated Output Power	Psat		52	-	-	dBm
Power Gain	Gp		8	-	-	dB
Work Efficiency	η		35	-	-	%
Gain Flatness	ΔG		-0.8	-	0.8	dB

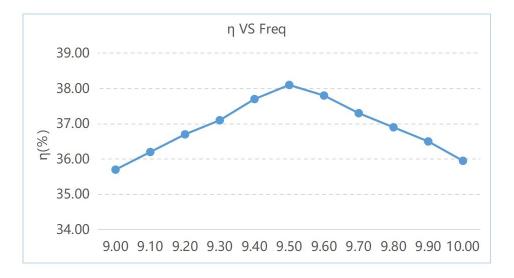


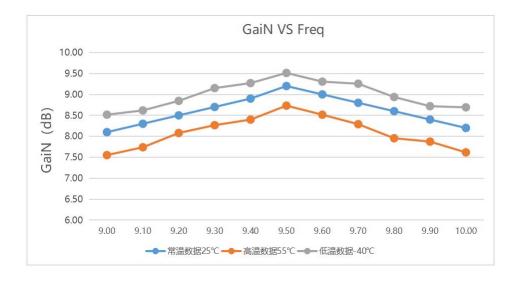
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Typical Curves





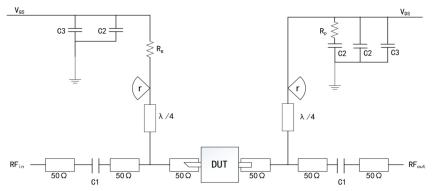




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Recommended Application Circuit



DUT: Device Under Test

 C1:1pF
 Rp:51Ω

 C2:1000pF
 Rg:15Ω

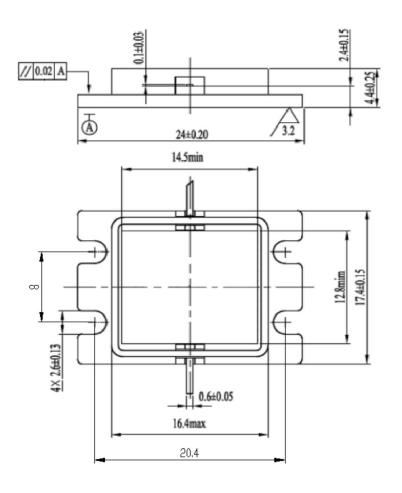
 C3:100uF

Radius ≈ 3.5mm (Rogers 5880, 20 mil)

ESD Level

ESD	Class III	2000V
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Overall Dimensions



Using Notes:

• During transportation and storage, ensure proper drying.

• During the use and assembly of the chip, take precautions against static electricity. Wear a grounded anti-static wristband.

• When powering on, apply gate voltage first, then apply leakage voltage.